



DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, mailing address and citizenship are as stated below, next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or any original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Single and Multiple Layer Packaging of High-Speed/High-Density ICs

the specification of which



is attached hereto; or

was filed on NOVEMBER 21, 2001 as

United States Application Number 09/990,247

or PCT International Application Number _____

and was amended on _____

(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment specifically referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or (f), or 365(b) of any foreign application(s) for patent, inventor's or plant breeder's rights certificate(s), or 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent, inventor's or plant breeder's rights certificate(s), or any PCT international application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s):

APPLICATION NUMBER	COUNTRY (OR INDICATE IF PCT)	DATE OF FILING (day, month, year)	PRIORITY CLAIMED	CERTIFIED COPY ATTACHED?
			<input type="checkbox"/> No <input type="checkbox"/> Yes	<input type="checkbox"/> No <input type="checkbox"/> Yes

I hereby claim the benefit under 35 U.S.C. 119(e) of any United States provisional application(s) listed below:

APPLICATION NUMBER	FILING DATE

I hereby claim the benefit under 35 U.S.C. 120 of any United States application(s) listed below:

APPLICATION NUMBER	FILING DATE	STATUS (ISSUED, PENDING, ABANDONED)

I hereby appoint Sierra Monolithics, Inc. at 103 West Torrance Blvd., Suite 102, Redondo Beach, CA 90277 USA and Soyeon P. Laub, Registration No. 39266, Telephone No. (949) 552-6910 (at the same address) (to whom all communications are to be directed) individually and collectively as my attorneys with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected herewith.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Sole/First Inventor:

(given name, middle initial, family name)

Binneg Y. Lao

Inventor's Signature

Date

Residence

Rancho Palos Verdes, CA

Citizenship

U.S.A.

(City, State)

(Country)

Mailing Address

29722 Grandpoint Lane, Rancho Palos Verdes, CA 90275

3

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Full Name of Second/Joint Inventor:
(given name, middle initial, family name)

William W. Chen

Inventor's Signature



Date 12/17/01

Residence Westchester, CA
(City, State)

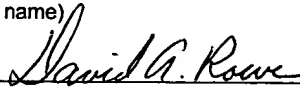
Citizenship U.S.A.
(Country)

Mailing Address 7816 Altavan Ave., Westchester, CA 90045

Full Name of Third/Joint Inventor:
(given name, middle initial, family name)

David A. Rowe

Inventor's Signature



Date 12-17-01

Residence Torrance, CA
(City, State)

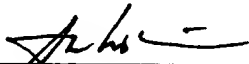
Citizenship U.S.A.
(Country)

Mailing Address 5309 Asteria Street, Torrance, CA 90503

Full Name of Fourth/Joint Inventor:
(given name, middle initial, family name)

Inho Kim

Inventor's Signature



Date December 4, 2001

Residence Palo Alto, CA
(City, State)

Citizenship U.S.A.
(Country)

Mailing Address 3772 Redwood Circle, Palo Alto, CA 94306

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(given name, middle initial, family name)

Binneg Y. Lao

Inventor's Signature _____

Date _____

Residence _____

Rancho Palos Verdes, CA
(City, State)

Citizenship _____

U.S.A.

(Country)

Mailing Address _____

29722 Grandpoint Lane, Rancho Palos Verdes, CA 90275

Full Name of Second/Joint Inventor:
(given name, middle initial, family name)

William W. Chen

Inventor's Signature _____

Date _____

Residence Westchester, CA
(City, State)

Citizenship U.S.A.
(Country)

Mailing Address 7816 Altavan Ave., Westchester, CA 90045

Full Name of Third/Joint Inventor:
(given name, middle initial, family name)

David A. Rowe

Inventor's Signature _____

Date _____

Residence Torrance, CA
(City, State)

Citizenship U.S.A.
(Country)

Mailing Address 5309 Asteria Street, Torrance, CA 90503

Full Name of Fourth/Joint Inventor:
(given name, middle initial, family name)

Inho Kim

Inventor's Signature _____

Date December 4, 2001

Residence Palo Alto, CA
(City, State)

Citizenship U.S.A.
(Country)

Mailing Address 3772 Redwood Circle, Palo Alto, CA 94306



#3

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the U.S. Patent Application of:	Examiner:
Serial No.: 09/990,247	Art Unit No.: 2811
Filing Date: November 21, 2001	Confirm. No.:
For: Single and Multiple Layer Packaging of High-Speed/High-Density ICs	
Inventor(s): Binneg Y. Lao et al.	

Correction of Inventionship
Written Consent of Assignee

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The inventive entity set forth in the declaration executed on November 20, 2001 for the above-referenced patent application was in error. The correct inventive entity for the above-referenced patent application includes:

Binneg Y. Lao, William W. Chen, David A. Rowe, and Inho Kim.

Sierra Monolithics, Inc. is the assignee of the entire right, title and interest in the above-referenced patent application. The assignment was recorded in the U.S. Patent and Trademark Office at Reel/Frame 012318/0520. Sierra Monolithics, Inc. hereby consents to the correction of inventionship.

The undersigned is authorized to act on behalf of the assignee.

Respectfully submitted,

Date: 3/19/02

SIERRA MONOLITHICS, INC.

by: Achim Hill
Achim Hill
CEO & President

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the U.S. Patent Application of:	Examiner:
Serial No.: 09/990,247	Art Unit No.: 2811
Filing Date: November 21, 2001	Confirm. No.:
For: Single and Multiple Layer Packaging of High-Speed/High-Density ICs	
Inventor(s): Binneg Y. Lao et al.	

Correction of Inventionship
Request to Correct Inventorship

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The inventive entity set forth in the declaration executed on November 20, 2001 for the above-referenced patent application was made in error. The correct inventive entity for the above-referenced patent application includes:

Binneg Y. Lao, William W. Chen, David A. Rowe, and Inho Kim.

Respectfully Submitted,

Date: 3/19/02

Soyeon (Karen) Pak Laub
Registration No. 39,266

SIERRA MONOLITHICS, INC.
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E-mail: klaub@monolithics.com

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the U.S. Patent Application of:	Examiner:
Serial No.: 09/990,247	Art Unit No.: 2811
Filing Date: November 21, 2001	Confirm. No.:
For: Single and Multiple Layer Packaging of High-Speed/High-Density ICs	
Inventor(s): Binneg Y. Lao et al.	

Correction of Inventionship ✓
Statement of Lack of Deceptive Intention

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The undersigned was not previously named as a joint inventor of the above-referenced patent application in error. This error in inventorship occurred without deceptive intention.

Respectfully Submitted,

Date: December 4, 2001



Inho Kim

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